

IN THE SPECIFICATION

**Please amend page 14, lines 13-30, as follows:**

Brief Description of the Drawings ~~Explanation of figures:~~

Figure 1: Vias before PER cleaning.

Figure 2: Vias after cleaning for 5 minutes - tank unit.

Figure 3: Vias after cleaning for 20 minutes - spray tool (Semitool SAT).

Figure 4: AlCu lines and vias after cleaning for 5 minutes at 45°C with a DSP solution (dilute sulfuric acid/peroxide) - spray tool (Semitool SAT).

Figure 5: Plot of mass removal of a sputtered Al/Cu layer as a function of exposure time. The solution used consisted of an aqueous solution of 5% of citric acid, 2% of peroxide, 1% of NMP. The dark curve shows removal without corrosion inhibitor. The pale line shows removal with addition of a corrosion inhibitor.

Figure 6: Plot of mass removal of a CVO-deposited tungsten layer as a function of exposure time. The solution used (see Figure 5).

Figure 7: Via and AlCu lines after cleaning for 20 minutes at 60°C with a solution of 5% tartaric acid, 1% NMP and 1000 ppm of enanthic acid.

Figure 8: Vias and AlCu lines after cleaning for 20 minutes at 60°C with a solution of 5% tartaric acid, 1% DMSO and 1000 ppm of enanthic acid.

Figure 9: Vias and AlCu lines after cleaning for 20 minutes at 60°C with a solution of 5% tartaric acid, 1% PGMEA and 1000 ppm of enanthic acid.

Figure 10: Via and AlCu lines after cleaning for 20 minutes at 60°C with a solution of 5% maleic acid, 1% NMP and 1000 ppm of enanthic acid.

Figure 11: Via and AlCu lines after cleaning for 20 minutes at 60°C with a solution of 5% maleic acid, 1% DMSO and 1000 ppm of enanthic acid.

Figure 12: Vias after cleaning for 20 minutes at 60°C with a solution of 5% maleic acid, 1% PGMEA and 1000 ppm of enanthic acid.

Figure 13: Plot of the etching rate (removal/time) of various coatings, with/ without addition of a corrosion inhibitor to the solution (see Figure 5).

Figure 14: Example 1 reference (post-ash residue) before cleaning - vias.

Figure 15: Example 1 reference (post-ash residue) before cleaning - AlCu lines.

Figure 16: Example 1 after cleaning - AlCu lines.

Figure 17: Example 1 after cleaning - via.

Figure 18: Example 2 after cleaning - AlCu lines.

Figure 19: Example 2 after cleaning - via.

Figure 20: Example 3, commercially available organic polymer remover, incipient etching of the AlCu metallisation was observed.

Figure 21: Example 3, present invention, no etching of the AlCu metallisation was observed.